SLOVENSKI STANDARD
oSIST prEN IEC 60749-7:2025

01-januar-2025

Polprevodniški elementi - Metode za mehansko in klimatsko preskušanje - 7. del: Merjenje količine notranje vlage in analiza drugih preostalih plinov

Semiconductor devices - Mechanical and climatic test methods - Part 7: Internal moisture content measurement and the analysis of other residual gases

Halbleiterbauelemente - Mechanische und klimatische Prüfverfahren - Teil 7: Messung des inneren Feuchtegehaltes und Analyse von anderen Restgasen

Dispositifs à semiconducteurs - Méthodes d'essais mécaniques et climatiques - Partie 7: Mesure de la teneur en humidité interne et analyse des autres gaz résiduels

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ICS:

31.080.01	Polprevodniški elementi (naprave) na splošno	Semiconductor devices in general

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SECRETARIAT: Korea, Republic of	SECRETARY: Mr Cheolung Cha
OF INTEREST TO THE FOLLOWING COMMITTEES:	HORIZONTAL FUNCTION(S):
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TITLE:

Semiconductor devices - Mechanical and climatic test methods - Part 7: Internal moisture content measurement and the analysis of other residual gases

PROPOSED STABILITY DATE: 2030

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SEMICONDUCTOR DEVICES – MECHANICAL AND CLIMATIC TEST METHODS –

Part 7: Internal moisture content measurement and the analysis of other residual gases

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International Standard IEC 60749-7 has been prepared by IEC technical committee 47: Semiconductor devices.

This third edition cancels and replaces the second edition published in 2011 and constitutes a technical revision. This third edition has been re-written and re-arranged to align it with the text of MIL-STD-883, method 1018.10.

The main technical change is the additional detail in the calibration requirements.

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53 The text of this standard is based on the following documents:

FDIS	Report on voting
47/xxxx/FDIS	47/yyyy/RVD

54

55 Full information on the voting for the approval of this standard can be found in the report on
56 voting indicated in the above table.

57 The language used for the development of this International Standard is English.

58 This publication has been drafted in accordance with the ISO/IEC Directives, Part 2, and
59 developed in accordance with ISO/IEC Directives, Part 1 and ISO/IEC Directives, IEC
60 Supplement, available at www.iec.ch/members_experts/refdocs. The main document types
61 developed by IEC are described in greater detail at www.iec.ch/publications.

62

63 A list of all parts in the IEC 60749 series, under the general title *Semiconductor devices –*
64 *Mechanical and climatic test methods*, can be found on the IEC website.

65 The committee has decided that the contents of this publication will remain unchanged until
66 the stability date indicated on the IEC web site under "http://webstore.iec.ch" in the data
67 related to the specific publication. At this date, the publication will be

68 • reconfirmed,
69 • withdrawn,
70 • replaced by a revised edition, or
71 • amended.

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